

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	7	input adj device with display adj device with CPU with system and "257"/\$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L5	0	input adj device with display adj device with CPU with system same interface and "257"/\$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L6	0	input adj device with display adj device with CPU with system same interfaced and "257"/\$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L7	1	input adj device with display adj device with CPU with system same interfaced	USPAT	OR	ON	2006/02/25 11:36
S1	1325	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 12:26
S2	959	(257/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 12:26
S3	215	S1 and heat with (lid cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:08
S4	160	S1 and heat with (lid cover)	USPAT	OR	ON	2006/02/24 12:26
S5	39	("20040012939" "4082394" "5166772" "5357404" "5490040" "5561265" "5566052" "5639989" "5703397" "5745344" "5748455" "5753857" "5804872" "5825634" "6008536" "6057600" "6063999" "6088231" "6137051" "6140577" "6198630" "6239359" "6252313" "6259609" "6269863" "6278617" "6288330" "6294731" "6324074" "6362477" "6400164" "6455925" "6483406" "6515870" "6518660" "6573590" "6597575" "6683796" "6703704").PN. OR ("6956285"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 14:39
S6	4	("5151771" "5172303" "5739581" "5963430").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 14:48
S7	4	("5539253").URPN.	USPAT	OR	ON	2006/02/24 14:52

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S8	192	S1 and conductive with (lid cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:58
S9	157	S1 and conductive with (lid cover)	USPAT	OR	ON	2006/02/24 14:54
S10	76	S9 not S4	USPAT	OR	ON	2006/02/24 14:54
S11	35	S8 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:58
S12	55	S3 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:01
S13	38	S12 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:01
S14	2	"20050127489".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:44
S15	41	S1 and substrate with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S16	4	("20030042598" "20040036183" "6317326" "6665187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:09
S17	0	S1 and interposer with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S18	0	S1 and bard with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11

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S19	0	S2 and bard with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S20	3	S2 and board with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S21	5	S1 and board with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S22	2081	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 16:12
S23	8	S22 and substrate with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S24	127	S22 and substrate with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S25	52	("4574331" "4581675" "4764846" "5007841" "5027191" "5043794" "5241456" "5376825" "5432681").PN. OR ("5701233"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:40
S26	538	(257/710).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 16:40
S27	406	S26 and (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:41

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S28	58	S27 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S29	58	S27 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S30	64	S26 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S31	6	S30 not S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S32	505	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:31
S33	119	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity with substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 17:58
S34	115	S33 not S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:47
S35	43	("5266912" "5491362" "5552596" "5591959" "5608262" "5656856" "5734199" "5760478" "5783870" "5801448" "5804882" "5869894" "5909057" "5949135" "5963429" "5963430" "5973930" "5977640" "6002178" "6005292" "6014316" "6025648" "6057598" "6084308" "6181008").PN. OR ("6369448"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:50

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S36	8	("20030148554" "5910682" "6081028" "6265771" "6339254" "6369448" "6590281" "6665187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:52
S37	1	"6965163".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S38	0	"6794748".p[n.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S39	1	"6794748".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S40	4	("5910682" "6265771" "6339254" "6665187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:54
S41	31	("5977640" "6127726" "6137164" "6147401" "6150724").PN. OR ("6339254").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:54
S42	0	("6794748").URPN.	USPAT	OR	ON	2006/02/24 16:55
S43	23	("3777221" "5375042" "5477933" "5535101").PN. OR ("5973930").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:57
S44	11	("5222014" "5614766" "5712769" "5801072" "5847936" "5973930" "5994166" "6150724" "6239385" "6294407").PN. OR ("6665194").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:58
S45	6	("4733461" "5040992" "5259784" "5575686").PN. OR ("5712769").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:59
S46	15	("20030205826" "5138436" "5786979" "6150724" "6222276" "6225699" "6228682" "6274214" "6281042" "6313998" "6369444" "6369448" "6400008" "6413353" "6418029").PN. OR ("6873035").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 17:02
S47	2	("6740980").URPN.	USPAT	OR	ON	2006/02/24 17:03
S48	2	("6740980").URPN.	USPAT	OR	ON	2006/02/24 17:04
S49	40	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:00
S50	104154	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package) and package within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:01

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S51	73	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package) and package with within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:01
S52	33	S51 not S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:03
S53	8	and\$1j\$2.xa. and socket	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:03
S54	64	("3326726" "3337838" "3366915" "3444506" "3848221" "4274700" "4487463" "4530002" "4572604" "4616406" "4654472" "4655526" "4667220" "4698663" "4724472" "4734042" "4820207" "4897055" "4943846" "4959750" "4970577" "4975066" "4997376" "5015207" "5037311" "5071363" "5081563" "5106461" "5110760" "5117069" "5123164" "5137456" "5200357" "5281151" "5309024" "5326936" "5330372" "5334279" "5342999" "5351393" "5371404" "5376825" "5390412" "5418471" "5508556" "5536362" "5569955" "5575688" "5578870" "5593322" "5611884" "5634821" "5639247" "5641309" "5645433" "5646442" "5702255" "5824950" "5854512" "6097086").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 18:05
S55	14	(US-20050073054-\$).did. or (US-6956285-\$ or US-6856013-\$ or US-5285012-\$ or US-6861292-\$ or US-6339254-\$ or US-6876066-\$ or US-6777794-\$ or US-6665194-\$ or US-5712769-\$ or US-6558978-\$ or US-6873035-\$ or US-5611884-\$ or US-5786628-\$).did.	US-PGPUB; USPAT	OR	ON	2006/02/24 18:10
S56	1	S55 and radu	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:10

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S57	14	(US-20050073054-\$.did. or (US-6956285-\$. or US-6856013-\$. or US-5285012-\$. or US-6861292-\$. or US-6339254-\$. or US-6876066-\$. or US-6777794-\$. or US-6665194-\$. or US-5712769-\$. or US-6558978-\$. or US-6873035-\$. or US-5611884-\$. or US-5786628-\$.did.	US-PGPUB; USPAT	OR	ON	2006/02/24 18:31
S58	18	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package).ab. and board with bump with socket	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:34
S59	60	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package).ab. and mother adj board with bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:34
S60	2	jp-2000136979-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/25 09:47
S61	2	jp-2001319997-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/25 09:47